Core Solders "Non-Flux Sputtering Products"

Improved ALMIT FLUX SR-37 to prevent the scattering of both flux and solder balls in the soldering process.

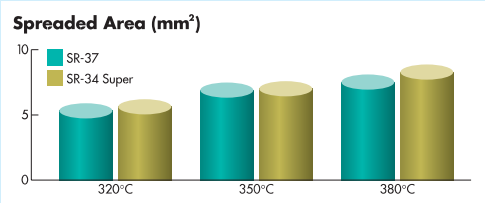
SR-37

1. Solderbility at the initial soldering stage, is specially excellent, following SR-34 SUPER that has better wettability and workability.
2. Sputtered flux amount is reduced to about 80~90%, as compared weith that of the ordinal Almit products.
3. Evolution of much fume and smell during the soldering process is completely prevented.

Examples of application : Sn-Ag-Cu solders Single-sided and through-hole substrates.

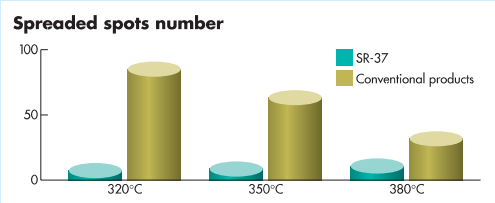
Comparison of spread areas

-Core solder dia. : 0.8Ø -Solder iron temp. : 320°C, 350°C, 380°C -Feeded amount : 50mm
-Feeding speed : 10mm/sec -Holding time : 0.5 sec. -Sample piece : 1piece <20 spots soldered>



Comparison of sputtered flux

-Core solder dia. : 0.8Ø -Solder iron temp. : 320°C, 350°C, 380°C -Feeded amount : 50mm
-Feeding speed : 10mm/sec -Holding time : 0.5 sec. -Sample piece : 3piece <20 spots soldered>



Comparison of spreaded area tests on the Cu plate as compared with that of other makers' products.

Insulation resistance test and Migration test

unit : (Ω)

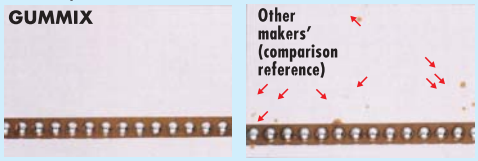
times		initial	500h	1000h	1500h
85°C / 85%RH	measured in vat	2.5×10^{12}	3.0×10^{9}	3.7×10^{9}	3.0×10^{9}
85°C / 85%RH / applied voltage 50V	measured in vat	2.5×10^{12}	3.1×10^{9}	3.3×10^{9}	3.9×10^{9}
60°C / 90%RH	measured out vat	6.4×10^{13}	5.8×10^{10}	3.1×10^{11}	4.0×10^{11}
60°C / 90%RH / applied voltage 100V	measured out vat	6.9×10^{13}	1.6×10^{11}	2.6×10^{11}	2.2×10^{11}

GUMMIX-19 Series
GUMMIX-19CH / GUMMIX-SB RMA

1. Possible to decrease all flux sputtering, ending zero value. 2. Non-peel off of flux residue on Cu plate after soldered.
3. Applicable to many parts and devices, such as optical Pickup, Relay, SW, and flexible substrates, etc.

Examples of application : Sn-Ag-Cu solders Pickup, Relay, and SW.

Comparison of sputtered flux



Non-peel off of the flux residues

Product name component for Core Solders

(Example) SR-37 LFM-48 3.5% 0.3Ø

Flux name; alloy type; flux content; core solder diameter

Core Solder products specification

Flux name	Alloy type	Flux content	Melting point temperature	Core solder diameter (mmØ)
SR-37	LFM-48 (Sn-3.0Ag-0.5Cu)	3.5%	217-220°C	0.3, 0.38, 0.5, 0.65, 0.8, 1.0, 1.2, 1.6
GUMMIX-19CH	LFM-48 (Sn-3.0Ag-0.5Cu)	3.5%	217-220°C	0.3, 0.38, 0.5, 0.65, 0.8, 1.0, 1.2, 1.6
GUMMIX-SB RMA	LFM-48 (Sn-3.0Ag-0.5Cu)	3.5%	217-220°C	0.3, 0.38, 0.5, 0.65, 0.8, 1.0, 1.2, 1.6

*LFM-48 has bean approved for JP PAT No.3027441 and US PAT No.5527628. *If the ordered core solder diameter is out of stock, please contact with our sales representative.

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